LOW-PROFILE **BLADE AND BEAN**



(0.50 mm) .0197" PITCH • LTH/LSH SERIES

LTH Mates:

LSH

LSH Mates:

NO. OF POSITIONS LTH **PER ROW**

-010, -020,

-030, -040, -050

01

PLATING OPTION

-G

= 10 µ"

(0.25 µm) Gold

(1.68)

066

(5.05)

OPTION

-K = (5.50 mm) .217" DIA Polyimide film Pick &

Place Pad -TR = Tape & Reel

-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

SPECIFICATIONS

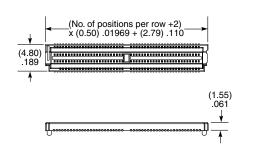
Insulator Material: Liquid Crystal Polymer Terminal Material: Phosphor Bronze Contact Material:

Plating: Au over 50 μ" (1.27 μm) Ni Current Rating: 2.6 A per pin (2 pins powered) Operating Temp Range: -55 °C to +125 °C

PROCESSING

Lead-Free Solderable:

Yes SMT Lead Coplanarity: (0.10 mm) .004" max Board Stacking:



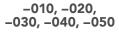
For applications requiring more than two connectors per board, contact ipg@samtec.com



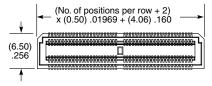
MATED HEIGHT

LEAD STYLE MATED HEIGHT* (2.31 mm) .091"

*Processing conditions will affect mated height.



-G = 10 µ" (0.25 µm)







-K = (7.50 mm) .295" DIA Polyimide film Pick & Place Pad

-TR = Tape & Reel

-FR

= Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

Note:

Some lengths, styles and options are non-standard, non-returnable.